



烜芯微
XUANXINWEI

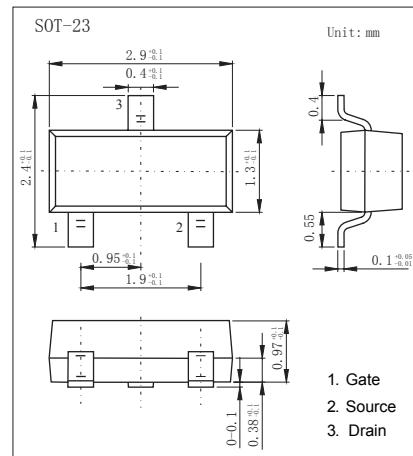
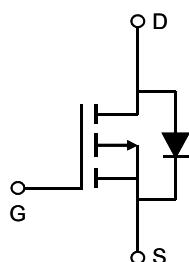
SMD Type

MOSFET

P-Channel MOSFET AO3413

■ Features

- $V_{DS} (V) = -20V$
- $I_D = -3 A (V_{GS} = -4.5V)$
- $R_{DS(ON)} < 80m\Omega (V_{GS} = -4.5V)$
- $R_{DS(ON)} < 100m\Omega (V_{GS} = -2.5V)$
- $R_{DS(ON)} < 130m\Omega (V_{GS} = -1.8V)$



■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current	I_D	-3	A
		-2.4	
Pulsed Drain Current	I_{DM}	-15	
Power Dissipation	P_D	1.4	W
		0.9	
Thermal Resistance.Junction- to-Ambient	R_{thJA}	90	°C/W
		125	
Thermal Resistance.Junction- to-Lead	R_{thJL}	80	
Junction Temperature	T_J	150	
Junction Storage Temperature Range	T_{stg}	-55 to 150	°C



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■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DSS}	$I_D=-250 \mu\text{A}, V_{GS}=0\text{V}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$			-1	μA
		$V_{DS}=-20\text{V}, V_{GS}=0\text{V}, T_J=55^\circ\text{C}$			-5	
Gate-Body leakage current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=-250 \mu\text{A}$	-0.4		-1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5\text{V}, I_D=-3\text{A}$			80	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-3\text{A}, T_J=125^\circ\text{C}$			115	
		$V_{GS}=-2.5\text{V}, I_D=-2.6\text{A}$			100	
		$V_{GS}=-1.8\text{V}, I_D=-1\text{A}$			130	
On state drain current	$I_{D(\text{ON})}$	$V_{GS}=-4.5\text{V}, V_{DS}=-5\text{V}$	-15			A
Forward Transconductance	g_{FS}	$V_{DS}=-5\text{V}, I_D=-3\text{A}$		12		S
Input Capacitance	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=-10\text{V}, f=1\text{MHz}$		560	745	pF
Output Capacitance	C_{oss}			80		
Reverse Transfer Capacitance	C_{rss}			70		
Gate resistance	R_g	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		15	23	Ω
Total Gate Charge	Q_g	$V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}, I_D=-3\text{A}$		8.5	11	nC
Gate Source Charge	Q_{gs}			1.2		
Gate Drain Charge	Q_{gd}			2.1		
Turn-On DelayTime	$t_{d(on)}$	$V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}, R_L=3.3\Omega, R_{GEN}=6\Omega$		7.2		ns
Turn-On Rise Time	t_r			36		
Turn-Off DelayTime	$t_{d(off)}$			53		
Turn-Off Fall Time	t_f			56		
Body Diode Reverse Recovery Time	t_{rr}	$I_F=-3\text{A}, dI/dt=100\text{A}/\mu\text{s}$		37	49	nC
Body Diode Reverse Recovery Charge	Q_{rr}			27		
Maximum Body-Diode Continuous Current	I_s				-1.4	A
Diode Forward Voltage	V_{SD}	$I_s=-1\text{A}, V_{GS}=0\text{V}$			-1	V

* The static characteristics in Figures 1 to 6 are obtained using <300us pulses, duty cycle 0.5% max.

■ Marking

Marking	AD*
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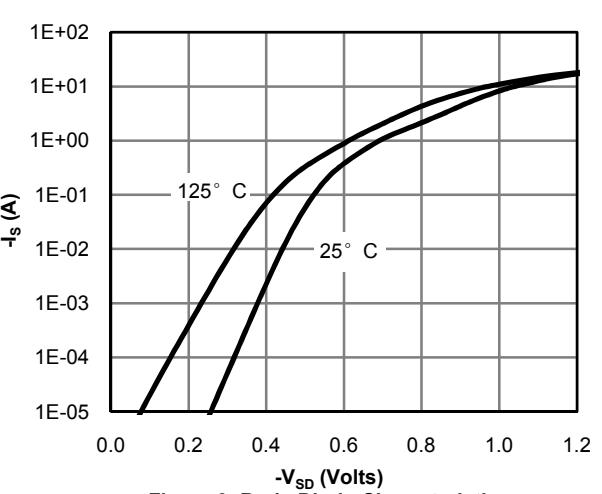
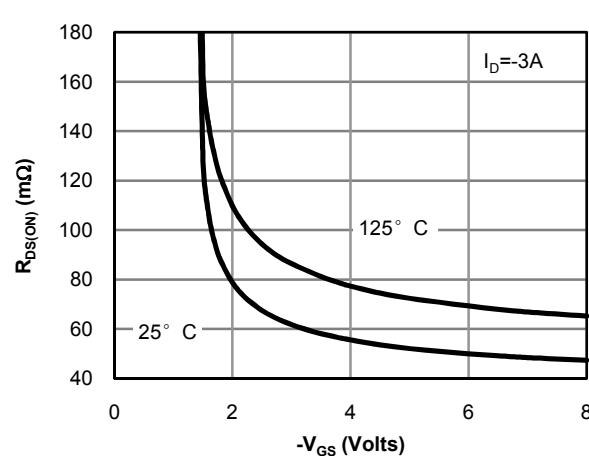
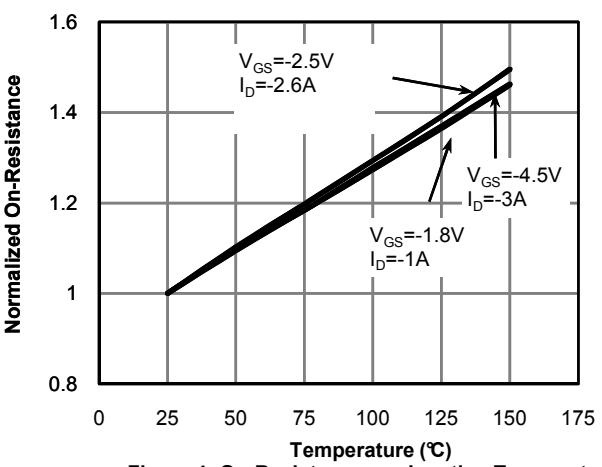
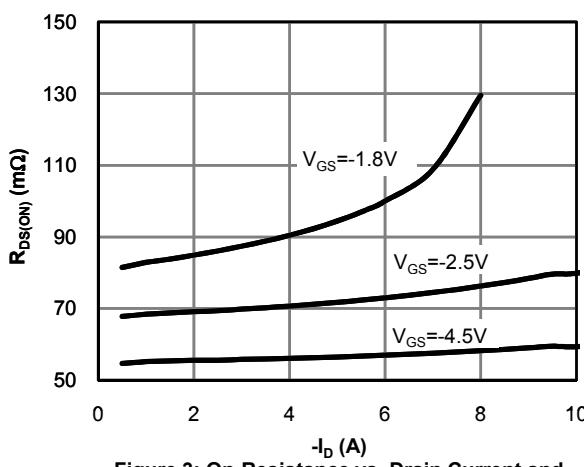
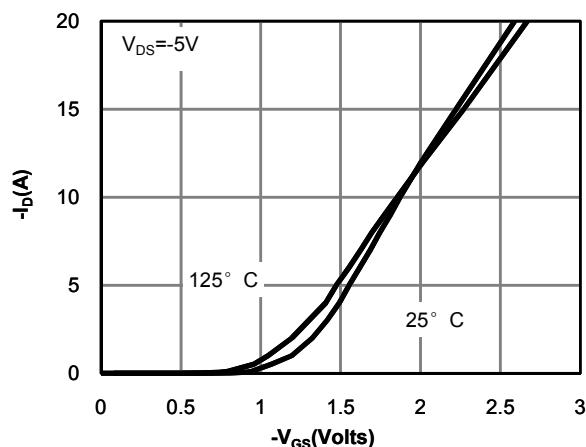
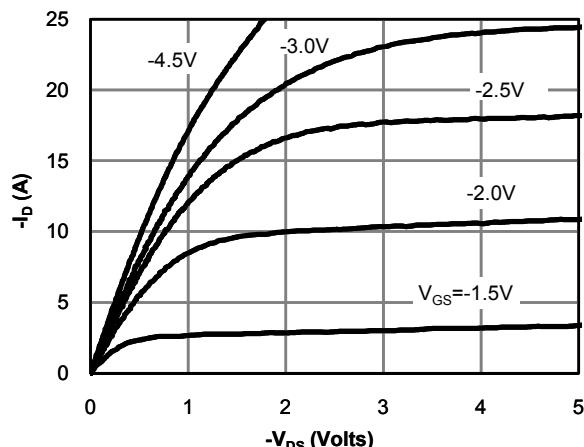
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■ Typical Characteristics





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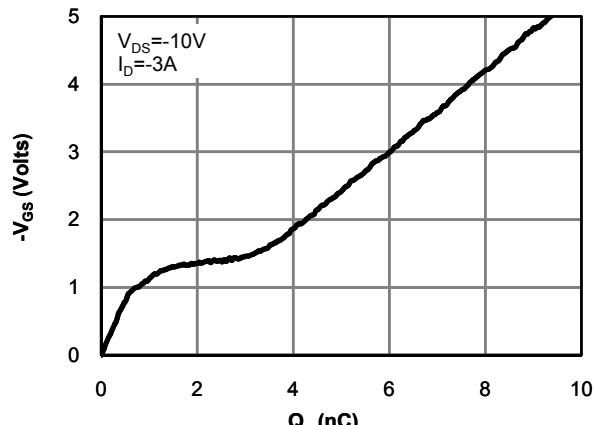


Figure 7: Gate-Charge Characteristics

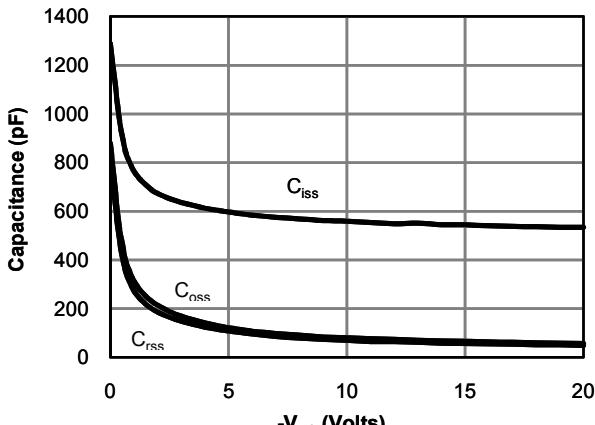


Figure 8: Capacitance Characteristics

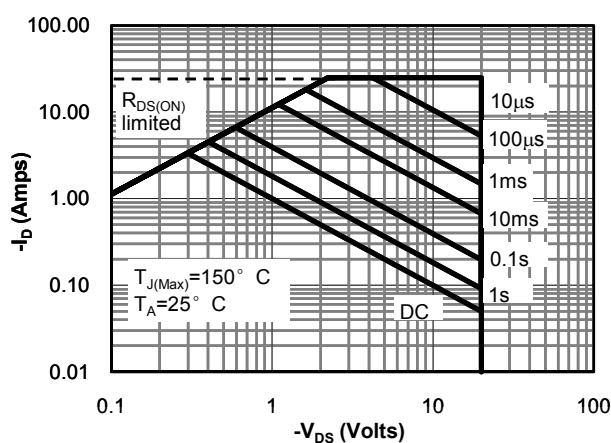


Figure 9: Maximum Forward Biased Safe Operating Area

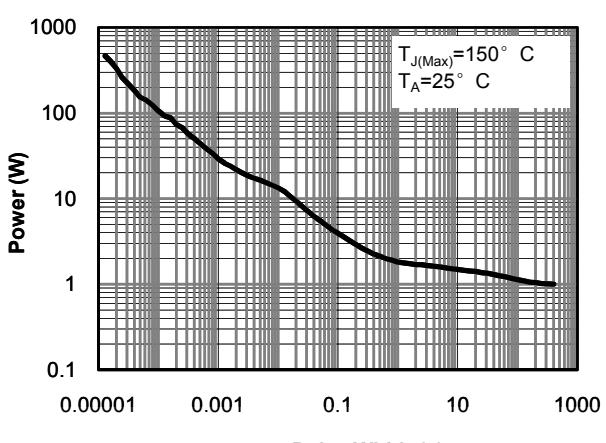


Figure 10: Single Pulse Power Rating Junction-to-Ambient

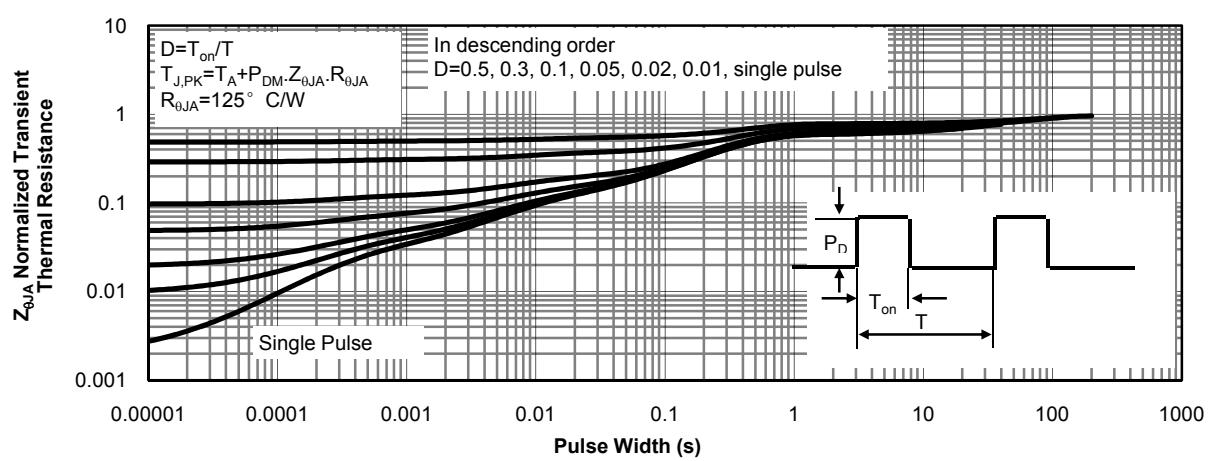


Figure 11: Normalized Maximum Transient Thermal Impedance (Note E)